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(Contd)

17. (New) The wafer of claim 11 and the plurality of the glide heads comprising a transducer mounted on a surface opposite the air bearing surfaces of the plurality of glide heads.

18. (New) The wafer of claim 11 wherein the contoured surface for the air bearing surfaces for the plurality of glide heads has a flatness less than about 0.5μ inch.

19. (New) A glide head sliced from the wafer of claim 11 wherein the contoured surface forms a raised bearing surface of the glide head.

20. (New) A detection system for detecting asperities having the glide head of claim 19 supported on an armature operable to position the glide head over a disc surface for glide testing and including a transducer on the glide head to detect interactions between the glide head and the disc surface.
